THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance – Junction–to–Case	$R_{\theta JC}$	6	°C/W
Thermal Resistance – Junction–to–Ambient (Note 1)	$R_{\theta JA}$	80	°C/W

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage Drop (Note 2) (i_F = 3 Amps, T_J = 25°C) (i_F = 3 Amps, T_J = 125°C)	v_F	 0.95 0.75	Volts
Maximum Instantaneous Reverse Current (Note 2) (T_J = 25°C, Rated dc Voltage) (T_J = 125°C, Rated dc Voltage)	i_R	 5 500	μA
Maximum Reverse Recovery Time (I_F = 1 Amp, di/dt = 50 Amps/μs, V_R = 30 V, T_J = 25°C) (I_F = 0.5 Amp, i_R = 1 Amp, I_{REC} = 0.25 A, V_R = 30 V, T_J = 25°C)	t_{rr}	 35 25	ns

1. Rating applies when surface mounted on the minimum pad sizes recommended.
2. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

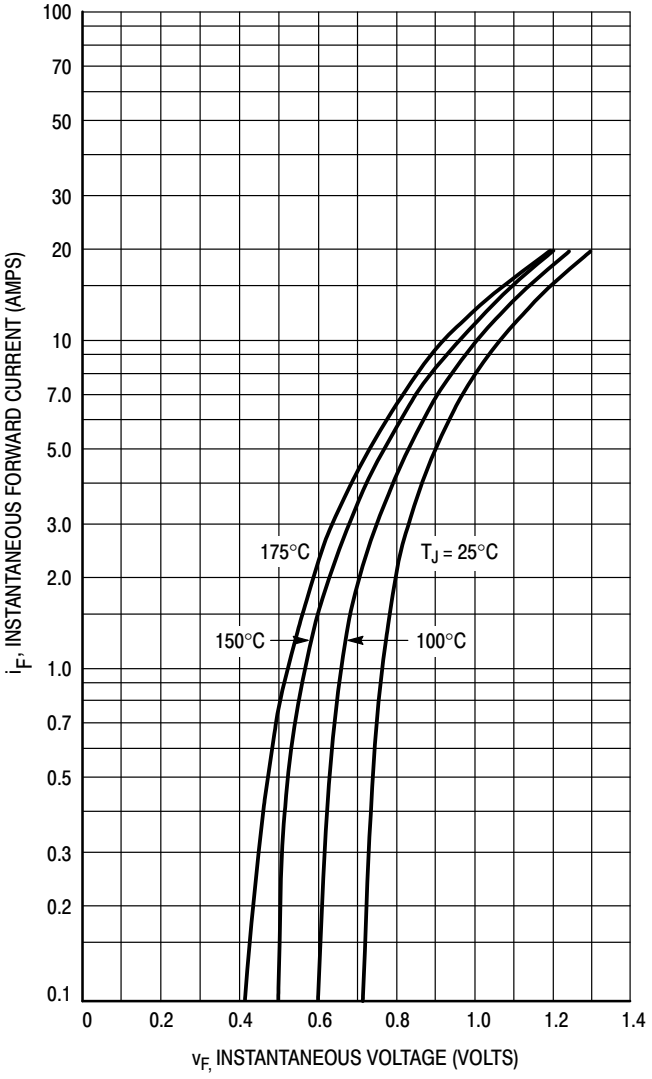


Figure 1. Typical Forward Voltage

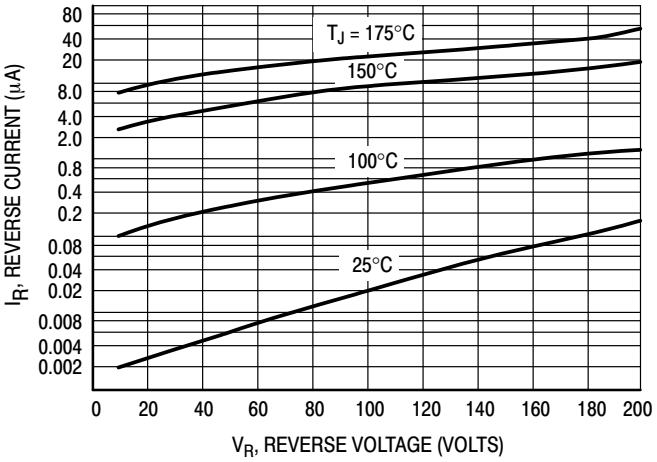


Figure 2. Typical Reverse Current*

* The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these curves if V_R is sufficiently below rated V_R.

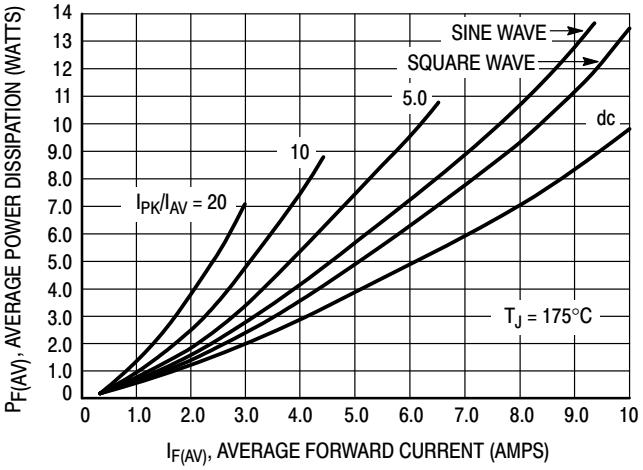


Figure 3. Average Power Dissipation

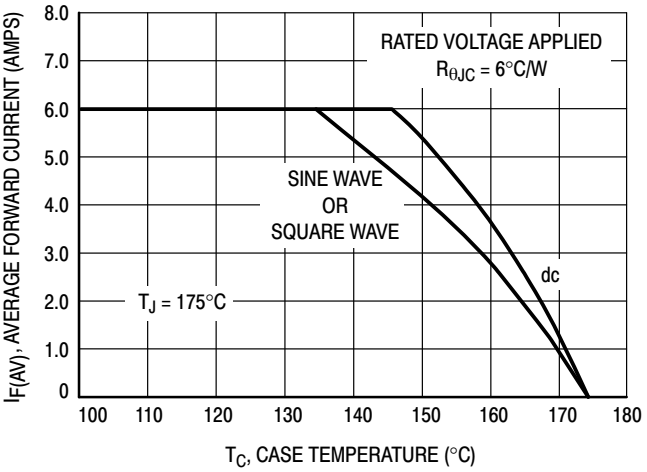


Figure 4. Current Derating, Case

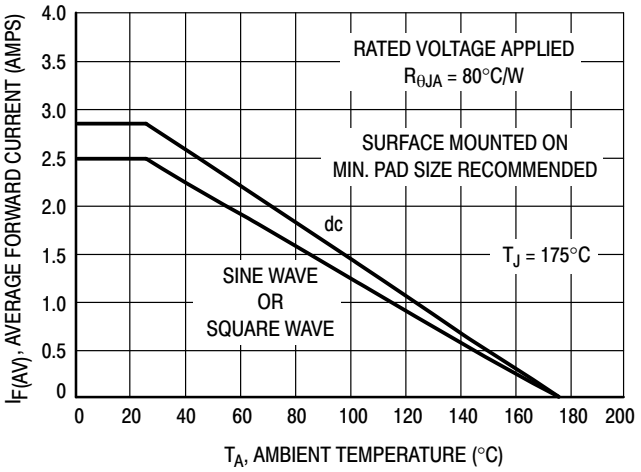


Figure 5. Current Derating, Ambient

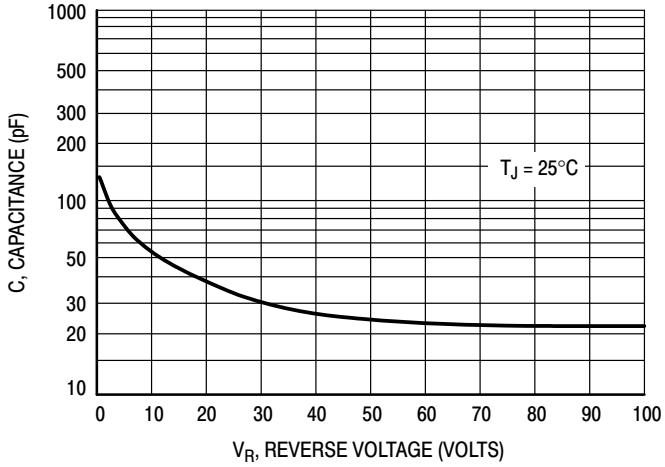
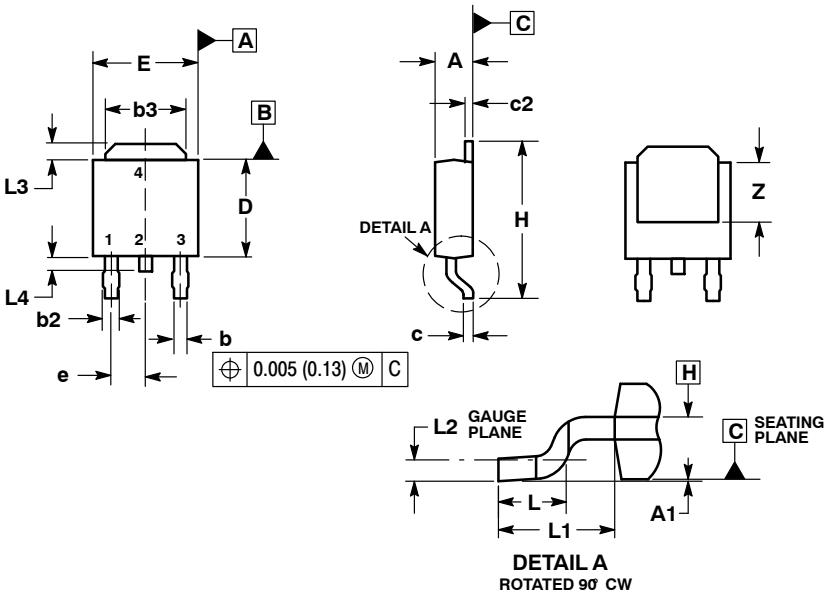


Figure 6. Typical Capacitance

PACKAGE DIMENSIONS

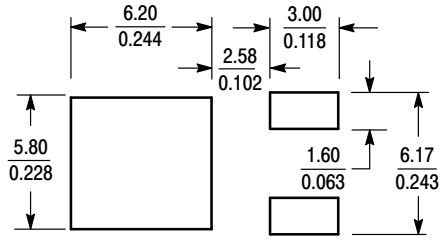
DPAK (SINGLE GAUGE)
CASE 369C−01
ISSUE D



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	−−−	0.040	−−−	1.01
Z	0.155	−−−	3.93	−−−

SOLDERING FOOTPRINT*



SCALE 3:1 (mm / inches)

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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